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APPLICATION NO.	FILING DATE	FIRST NAMED INVENTOR	ATTORNEY DOCKET NO.	CONFIRMATION NO.		
10/007,839	11/08/2001	Theodore W. Houston	TI-23546	7628		
23494	7590 12/17)2				
TEXAS INSTRUMENTS INCORPORATED			EXAM	EXAMINER		
P O BOX 65 DALLAS, T	5474, M/S 3999 X 75265		SCHILLINGER, LAURA M			
			ART UNIT	PAPER NUMBER		
			2813			

DATE MAILED: 12/17/2002

Please find below and/or attached an Office communication concerning this application or proceeding.

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		.Application No.	Applicant(s)	•			
	Office Action Commence	10/007,839	HOUSTON ET AL.				
	Office Action Summary	Examiner	Art Unit				
·· ······	The MAN INC. DATE CO.	Laura M Schillinger	2813				
Period fe	The MAILING DATE of this communication app or Reply	pears on the cover sheet with t	the correspondence addres	ss			
THE - Exte after - If th - If NO - Failt - Any	MAILING DATE OF THIS COMMUNICATION. MAILING DATE OF THIS COMMUNICATION. SIX (6) MONTHS from the mailing date of this communication. Experied for reply specified above is less than thirty (30) days, a reply of period for reply is specified above, the maximum statutory period vare to reply within the set or extended period for reply will, by statute reply received by the Office later than three months after the mailing ed patent term adjustment. See 37 CFR 1.704(b).	36(a). In no event, however, may a reply y within the statutory minimum of thirty (3t vill apply and will expire SIX (6) MONTHS cause the application to become ABANI	be timely filed be timely filed be days will be considered timely. from the mailing date of this community construction (35 U.S.C. & 133)	ınication.			
1)⊠	Responsive to communication(s) filed on 25 J	lune 2002 .					
2a)⊠	This action is FINAL . 2b) Th	is action is non-final.					
3)	·						
Disposit	ion of Claims	•	,				
4)⊠	Claim(s) <u>1-14</u> is/are pending in the application						
	4a) Of the above claim(s) is/are withdrawn from consideration.						
5)	Claim(s) is/are allowed.						
6)⊠	Claim(s) <u>1-14</u> is/are rejected.						
7)	Claim(s) is/are objected to.						
	Claim(s) are subject to restriction and/or ion Papers	r election requirement.					
9)	The specification is objected to by the Examine	г.					
10)	The drawing(s) filed on is/are: a)□ accep	oted or b) objected to by the	Examiner.				
	Applicant may not request that any objection to the	e drawing(s) be held in abeyance	e. See 37 CFR 1.85(a).				
11) The proposed drawing correction filed on is: a) approved b) disapproved by the Examiner.							
	If approved, corrected drawings are required in rep	oly to this Office action.					
12)	The oath or declaration is objected to by the Exa	aminer.					
Priority ι	ınder 35 U.S.C. §§ 119 and 120						
13)	Acknowledgment is made of a claim for foreign	priority under 35 U.S.C. § 11	19(a)-(d) or (f).				
a)	☐ All b)☐ Some * c)☐ None of:						
	1. Certified copies of the priority documents have been received.						
	2. Certified copies of the priority documents have been received in Application No						
* 5	3. Copies of the certified copies of the prior application from the International Bur See the attached detailed Office action for a list of the control of the certification of the prior application of the certification of the prior application of the certification of the certificat	reau (PCT Rule 17.2(a)).		je			
	acknowledgment is made of a claim for domestic	•		olication).			
_a) The translation of the foreign language protection of the foreign language protection. Acknowledgment is made of a claim for domestic	visional application has been	received.				
, ایبارہ. Attachmen		5 priority under 00 0.0.0. 33	123 GHAIOF 121.				
1) Notic 2) Notic	e of References Cited (PTO-892) e of Draftsperson's Patent Drawing Review (PTO-948) nation Disclosure Statement(s) (PTO-1449) Paper No(s)	5) Notice of Inform	mary (PTO-413) Paper No(s) mal Patent Application (PTO-152				
	1.50						

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DETAILED ACTION

This Action is in response to the Applicant's Appeal Brief filed 9/30/02 in Paper No.7.

Claim Rejections - 35 USC § 102

The following is a quotation of the appropriate paragraphs of 35 U.S.C. 102 that form the basis for the rejections under this section made in this Office action:

A person shall be entitled to a patent unless -

(b) the invention was patented or described in a printed publication in this or a foreign country or in public use or on sale in this country, more than one year prior to the date of application for patent in the United States.

Claims 1-14 are rejected under 35 U.S.C. 102(b) as being anticipated by Blewer ('200).

In reference to claim 1, Blewer teaches a method comprising:

- a) forming a structure (Fig.4 (5)) having porous semiconductor material at a first surface thereof (Fig.4 (4));
- b) sealing the surface (Col.4, lines: 19-22- which teaches densification of the oxidized porous silicon- this densification acts to seal the OPS layer from subsequent HF etching);
 - c) forming an epitaxial semiconductor layer on the porous material (Col.2, lines: 5-10),
- c) implanting an oxidizing species into the porous semiconductor material after step b (Col.1, lines: 30-45),
- d) reacting the oxidizing species with the porous semiconductor material to form a buried dielectric layer beneath the epitaxial layer (Col.2, lines: 10-20).

In reference to claim 2, Blewer teaches wherein the oxidizing species consists of O (col.2, lines: 10-20).

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In reference to claim 3, Blewer teaches wherein the semiconductor layer consists of Si (Col.2, lines: 10-15).

In reference to claim 4, Blewer teaches a method comprising:

- a) anodizing a Si wafer to form porous Si (Col.3, lines: 50-55 and Col.2, lines: 30-45);
- b) sealing the surface(Col.4, lines: 19-22- note that steam is heated H₂O);;
- c) forming an epitaxial semiconductor layer on the porous material (Col.2, lines: 5-10),
- c) implanting an oxidizing species into the porous semiconductor material after step b (Col.1, lines: 30-45),
- d) reacting the oxidizing species with the porous semiconductor material to form a buried dielectric layer beneath the epitaxial layer (Col.2, lines: 10-20).

In reference to claim 5, Blewer teaches wherein the semiconductor layer consists of Si (Col.2, lines: 10-15).

In reference to claim 6, Blewer teaches a method comprising:

- a) partially anodizing a Si wafer to form porous Si (Col.3, lines: 30-60);
- b) sealing the surface(Col.4, lines: 19-22);
- c) forming an epitaxial semiconductor layer on the porous material (Col.2, lines: 5-10),

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- c) implanting an oxidizing species into the porous semiconductor material after step b(Col.1, lines: 30-45),
- d) reacting the oxidizing species with the porous semiconductor material to form a buried dielectric layer beneath the epitaxial layer (Col.2, lines: 10-20).

In reference to claim 7, Blewer teaches wherein the oxidizing species consists of O (Col.2, lines: 10-20).

In reference to claim 8, Blewer teaches wherein the semiconductor layer consists of Si(Col.2, lines: 10-15).

In reference to claim 9, Blewer teaches the device as a result of claim 1 (linking claim-automatically rejected with claim 1).

In reference to claim 10, Blewer teaches the device as a result of claim 4 (linking claim-automatically rejected with claim 4).

In reference to claim 11, Blewer teaches the device as a result of claim 6 (linking claim-automatically rejected with claim 6).

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In reference to claim 12, wherein sealing includes heating the porous semiconductor in a H ambient (Col.4, lines: 19-22- note that steam is heated H₂O);

In reference to claim 13, wherein sealing includes heating the porous semiconductor in a H ambient(Col.4, lines: 19-22- note that steam is heated H₂O);

In reference to claim 14, wherein sealing includes heating the porous semiconductor in a H ambient(Col.4, lines: 19-22- note that steam is heated H₂O);

Response to Arguments

Applicant's arguments filed 9/30/02 have been fully considered but they are not persuasive. Applicant's arguments reflect a misunderstanding of the Examiner's prior art rejection. To be clear, Blewer teaches densifying porous silicon through a steam treatment. (Col.4, lines: 19-25). The densification step taught by Blewer is equivalent to "sealing" as claimed by the applicant. Claims must be given their broadest reasonable interpretation, the term sealing as defined by Merriam-Webster's Collegiate Dictionary Tenth Edition (1998) means "to close or make secure against access, leakage, or passage by a fastening or coating". Blewer teaches that oxidized porous silicon has a high etch rate and densification is necessary to prevent this. Therefore, densification makes the porous silicon layer substantially secure against access, leakage or passage of the hydrofluoric acid. Therefore, densification is "sealing" as claimed by the Applicant.

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Applicant's assertion that the Examiner's rejection of the sealing step was predicated

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upon "steam" is incorrect. The steam constitutes the heated hydrogen ambient. In light of

Applicant's confusion the Examiner has elected to reopen prosecution to clarify matters prior to

taking such misconceptions to the Board of Appeals.

Conclusion

Any inquiry concerning this communication or earlier communications from the

examiner should be directed to Laura M Schillinger whose telephone number is (703) 308-6425.

The examiner can normally be reached on M-T, R-F 7:00-5:00.

If attempts to reach the examiner by telephone are unsuccessful, the examiner's

supervisor, Carl W Whitehead, Jr. can be reached on (703) 308-4940. The fax phone numbers

for the organization where this application or proceeding is assigned are (703) 308-7722 for

regular communications and (703) 308-7722 for After Final communications.

Any inquiry of a general nature or relating to the status of this application or proceeding

should be directed to the receptionist whose telephone number is (703) 308-1500.

LMS

December 16, 2002

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